

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	578	lithography and process adj margin\$1	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 13:26
L2	1	l1 and ed-tree\$2	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 13:37
L3	12331	716/21,19.ccls. or 430/5,311,312.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 13:38
L4	140	l3 and process adj margin	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 13:41
L5	109	l4 and (lithography or photolithography)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 13:41
L6	8	l5 and dispersion	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 13:41
L7	4664	700/121.ccls. or 355/53.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 13:41
L8	2607	l7 and (lithography or photolithography)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 13:41
L9	21	l8 and process adj margin	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 13:43
L10	1	"6760892".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 13:43
L11	6	("20020188925" "20030126581" "4835704" "5740068" "6289499" "6584609").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/09 13:43
L12	0	("6760892").URPN.	USPAT	OR	OFF	2005/08/09 13:44
L13	1856	716/4.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 13:46
L14	10	l13 and process adj margin\$1	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 13:48
L15	18	evaluat\$3 with (process adj margin\$1)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 13:51
L16	180	focus adj position and (lithography or photolithography) and pattern and dispersion	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 13:51
L17	35	l16 and height with (wafer or substrate)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 13:52
L18	1	l17 and margin adj curve\$2	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 13:51
L19	10	(US-20040233407-\$ or US-20020188925-\$ or US-20010049811-\$ or US-20030208741-\$).did. or (US-5303002-\$ or US-6004701-\$ or US-6100515-\$ or US-6610460-\$ or US-6760892-\$ or US-6848096-\$).did.	US-PGPUB; USPAT	OR	OFF	2005/08/09 14:07
L20	2	l19 and height	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 14:44

L21	104	kosowski.xa.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 14:44
L22	0	l19 and pseudo	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 15:12
L23	1	l19 and dispersion	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 15:13
L24	2	l19 and height	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 15:13
L25	5	l19 and exposure same focus	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 15:13
S1	1538	process adj margin and pattern and (substrate or wafer)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/05 14:17
S2	117	S1 and dispersion	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/05 14:17
S3	32	S2 and height and exposure	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/08 14:48
S4	1	"l3" and ed-tree\$2	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/08 15:09
S5	31	ed-tree\$2	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/08 16:11
S6	6	S5 and process adj margin	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/08 16:44
S7	1	"20040233407"	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/08 16:21
S8	66	substrate same exposure adj parameters	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/08 16:21
S9	37	S8 and focus	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/08 16:23
S10	0	S9 and "depth of focus"	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/08 16:26
S11	6	S9 and (depth near2 focus)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/08 16:31
S12	4	S9 and dispersion	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/08 16:31
S13	9	700/121.ccls. and process adj margin	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/08 16:45
S14	5	(US-20040233407-\$).did. or (US-5303002-\$ or US-6004701-\$ or US-6100515-\$ or US-6610460-\$).did.	US-PGPUB; USPAT	OR	OFF	2005/08/09 11:32
S15	1	S14 and focus and pattern and dispersion	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/09 13:24